## N - Channel 30 V (D-S) MOSFET

PRODUCT SUMMARY						
V <sub>DS</sub> (V)	R <sub>DS(on)</sub> (mΩ)(Typ.)	I <sub>D</sub> (A) <sup>a</sup>	Q <sub>g</sub> (Typ.)			
30	10.5 at V <sub>GS</sub> = 10 V	26	4.2 nC			
50	15.5 at V <sub>GS</sub> = 4.5 V	36				

PDFN 3.3x3.3-8L Pin Configuration

### FEATURES

- DT-Trench MOSFET
- + 100 %  $\rm R_g$  and UIS Tested
- Fast Switching Speed
- Low Gate Charge

#### APPLICATIONS

· Battery charging and discharging for battery pack

· Power switch for Adaptor/ Charger

Top View	Bottom View			
$ \begin{array}{c} 8 & 7 & 6 & 5 \\ 0 & & & & \\ 1 & 2 & 3 & 4 \end{array} $	5 6 7 8 5 6 7 8 4 3 2 1	S       1       8       D         S       2       7       D         S       3       6       D         G       4       5       D	G C S S N-Channel MOSFET	
ABSOLUTE MAXIMUM	<b>RATINGS</b> (T <sub>C</sub> = 25 °	C, unless otherwise noted)		
PARAMETER		SYMBOL	LIMIT	U
Drain-Source Voltage		V <sub>DS</sub>	30	
Gate-Source Voltage		Vee	+ 20	

PARAMETER	SYMBOL	LIMIT	UNIT	
Drain-Source Voltage	V <sub>DS</sub>	30	V	
Gate-Source Voltage	V <sub>GS</sub>	± 20	v	
	T <sub>C</sub> = 25 °C	1	36	
Continuous Drain Current (T <sub>J</sub> = 150 °C) <sup>a</sup>	T <sub>C</sub> = 100 °C	I <sub>D</sub>	23	А
Pulsed Drain Current <sup>b</sup>	I <sub>DM</sub>	75		
Single Avalanche Energy	E <sub>AS</sub>	24	mJ	
Maximum Dawar Disaination	T <sub>C</sub> = 25 °C	P	26	w
Maximum Power Dissipation <sup>c</sup>	T <sub>C</sub> = 100 °C		10.4	vv
Operating Junction and Storage Temperature Range		T <sub>J</sub> , T <sub>stg</sub>	- 55 to +150	°C

THERMAL RESISTANCE RATINGS					
PARAMETER	SYMBOL	LIMIT	UNIT		
Junction-to-Ambient (PCB Mount) <sup>d</sup>	R <sub>thJA</sub>	75	°C/W		
Junction-to-Case (Drain)	R <sub>thJC</sub>	4.8			

Notes

- a. Calculated continuous current based on maximum allowablejunction temperature.
- b. Repetitive rating; pulse width limited by max. junction temperature.
- c. Pd is based on max. junction temperature, using junction-case thermal resistance.
- d. The value of ReuA is measured with the device mounted on 1 in 2 FR-4 board with 2oz. Copper, in a still air environment with Ta=25 °C.





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<b>SPECIFICATIONS</b> (T <sub>J</sub> = 25 °C, unless otherwise noted)						
PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNIT
Static						
Drain-Source Breakdown Voltage	V <sub>DS</sub>	$V_{DS}$ $V_{GS} = 0 \text{ V}, \text{ I}_{D} = 250 \mu\text{A}$		-	-	V
Gate Threshold Voltage	V <sub>GS(th)</sub>	$V_{DS} = V_{GS}$ , $I_D = 250 \ \mu A$	1.0	-	3.0	v
Gate-Body Leakage	I <sub>GSS</sub>	$V_{DS}=0~V,~V_{GS}=\pm~20~V$	-	-	± 100	nA
Zero Gate Voltage Drain Current	1	$V_{DS}$ = 30 V, $V_{GS}$ = 0 V	-	-	1	
Zero Gale Voltage Drain Gurrent	IDSS	$V_{DS} = 24 \text{ V}, V_{GS} = 0 \text{ V}, T_{J} = 55 ^{\circ}\text{C}$	-	-	5	μA
On-State Drain Current <sup>a</sup>	I <sub>D(on)</sub>	$V_{DS} \ge 5 V, V_{GS} = 5 V$	36	-	-	А
Drain-Source On-State Resistance <sup>a</sup>	Б	$V_{GS} = 10 \text{ V}, \text{ I}_{D} = 6 \text{ A}$	-	10.5	12.5	- mΩ
Drain-Source On-State Resistance *	R <sub>DS(on)</sub>	$V_{GS} = 4.5 \text{ V}, \text{ I}_{D} = 5 \text{ A}$	-	15.5	19	
Forward Transconductance <sup>a</sup>	9 <sub>fs</sub>	V <sub>DS</sub> = 5 V, I <sub>D</sub> = 12 A	-	32	-	S
Dynamic <sup>b</sup>				•		
Input Capacitance	C <sub>iss</sub>		-	396	-	pF
Output Capacitance	C <sub>oss</sub>	$V_{GS}$ = 0 V, $V_{DS}$ = 15 V, f = 1 MHz	-	260	-	
Reverse Transfer Capacitance	C <sub>rss</sub>		-	18	-	
Total Gate Charge <sup>c</sup>	Qg		-	8.8	-	
Gate-Source Charge <sup>c</sup>	Q <sub>gs</sub>	$V_{DS} = 15 \text{ V}, V_{GS} = 10 \text{ V}, I_D = 6 \text{ A}$	-	2.6	-	nC
Gate-Drain Charge <sup>c</sup>	Q <sub>gd</sub>		-	1.4	-	
Gate Resistance	R <sub>g</sub>	f = 1 MHz	-	2.1	-	Ω
Turn-On Delay Time <sup>c</sup>	t <sub>d(on)</sub>		-	13	-	
Rise Time <sup>c</sup>	t <sub>r</sub>	$V_{DS} = 15 \text{ V}, \text{ I}_{D} = 1 \text{ A}, \text{ R}_{g} = 1.5 \Omega$	-	6.3	-	20
Turn-Off Delay Time <sup>c</sup>	t <sub>d(off)</sub>	V <sub>GS</sub> = 10 V	-	21	-	ns
Fall Time <sup>c</sup>	t <sub>f</sub>		-	7	-	
Drain-Source Body Diode Ratings and	Characterist	<b>iics</b> <sup>b</sup> (T <sub>C</sub> = 25 °C)				
Continuous Source-Drain Diode Current	۱ <sub>S</sub>	T <sub>C</sub> = 25 °C	-	-	36	А
Pulsed Current (t = 100 µs)	Pulsed Current (t = 100 μs) I <sub>SM</sub>		-	-	75	А
Forward Voltage <sup>a</sup>	V <sub>SD</sub>	I <sub>F</sub> = 1 A, V <sub>GS</sub> = 0 V	-	-	1	V

Notes

a. Pulse test; pulse width  $\leq 300~\mu\text{s},$  duty cycle  $\leq 2~\%.$ 

b. Guaranteed by design, not subject to production testing.

c. Independent of operating temperature.

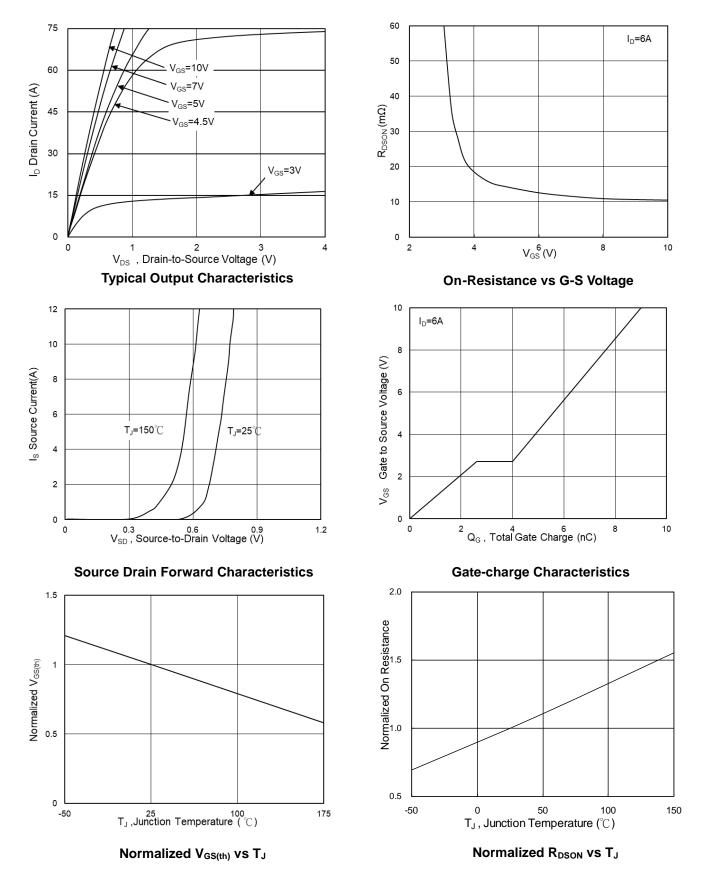
Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.



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### TYPICAL CHARACTERISTICS (25°C, unless otherwise noted)

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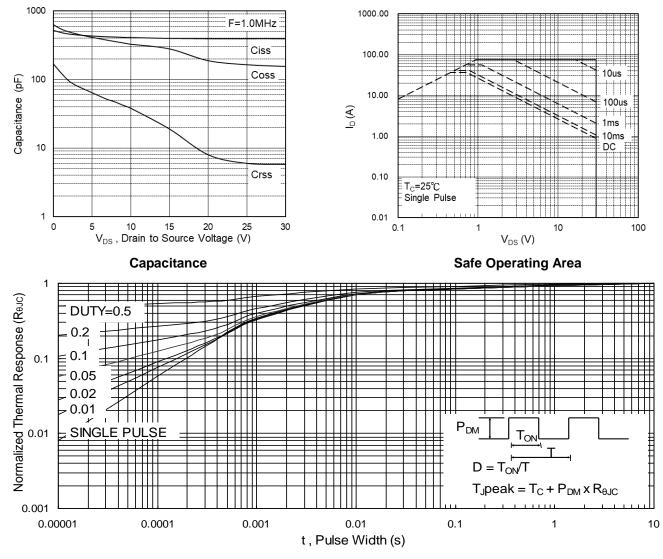




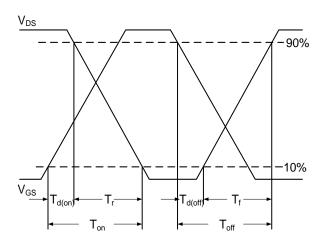
# **DTQ312N03PA**

### TYPICAL CHARACTERISTICS (25°C, unless otherwise noted)

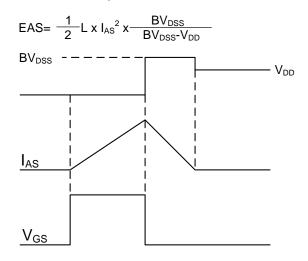




Normalized Maximum Transient Thermal Impedance



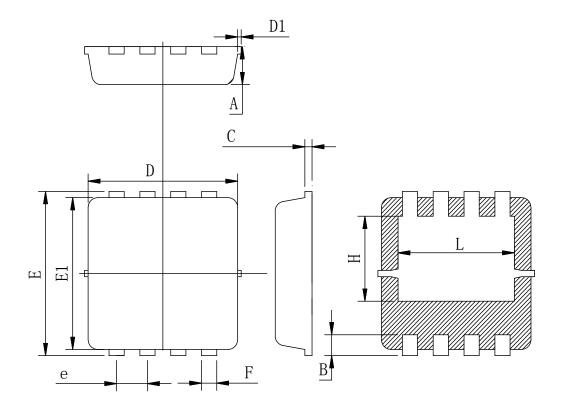
**Switching Time Waveform** 



**Unclamped Inductive Waveform** 

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# PDFN 3.3X3.3 PACKAGE OUTLINE



### COMMON DIMENSIONS (UNITS OF MEASURE=MILLIMETER)

Symbol	Min	Тур	Max
A	0.600	0.775	1.000
В	0.20	0.38	0.55
C	0.05	0.15	0.40
D	3.10	3.25	3.50
D1	-	-	0.15
E	3.15	3.35	3.50
E1	2.60	3.10	3.45
e	0.50	0.65	0.80
F	0.15	0.32	0.45
Н	1.25	1.73	2.10
L	2.20	2.45	2.85



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